TECHNICAL PROGRAM

TUESDAY, Oct. 24, 2023

7:30 a.m. - 8:00 a.m. Conference Registration

7:30 a.m. - 3:05 p.m. Technical Tour & Box Lunch

- Doosan Enerbility
- KIMM Busan Machinery Research Center

3:05 p.m. - 3:45 p.m. Keynote Presentation 5 Pioneering High Average Power Laser Technology at HiLASE Dr. Tomáš Mocek

(HiLASE Centre, Czech Republic)

3:45 p.m. - 4:00 p.m. Coffee Break

Innovative & Alternative Laser Peening Applications

Development of Commercial Laser Peening Systems / UNSM Systems / Cavitation Peening Systems / Water Jet Peening System / Ultrasonic Peening Systems, etc. Session Chair: Dr. Pratik Shukla (The Manufacturing Technology Centre, United Kingdom)

4:00 p.m. - 4:20 p.m. Oral Presentation A078

Laser Shock Peening Technology Development at HiLASE Center and Actual Capabilities Dr. Jan Brajer

(HiLASE Centre, Institute of Physics of the Czech Academy of Sciences, Czech Republic)

4:20 p.m. - 4:40 p.m. Oral Presentation A073

The FLASP Apparatus: Laser Peening with Record-Breaking Laser Energy at the Tip of a Fiber

Mr. Adam Ayeb

(Imagine Optic, France)

4:40 p.m. - 5:00 p.m. Oral Presentation A049

Development of a 10-mJ Handheld Microchip Laser and its Application to Laser Peening Mr. Shota Sekiguchi (Optoquest Co., Ltd., Japan)

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5:00 p.m. - 5:20 p.m. Oral Presentation A062

Microstructure Evolution and Electroplasticity in Ti64 Subjected to Electropulsing-Assisted Laser Shock Peening

Dr. Hao Zhang

(College of Civil Aviation, Northwestern Polytechnical University, China)

5:20 p.m. - 5:40 p.m. Oral Presentation A082

Considerations and Developments for the Commercialization of Laser Shock Peening Technology

Mr. Mark Bloomberg

(LSP Technologies, Inc., USA)

5:40 p.m. - 6:00 p.m. Oral Presentation A032

50J High Energy Nd: Glass Slab Laser for Shock Peening

Mr. Fang Zhang

(Beamtech Canada, Canada)

7:00 p.m. - 9:00 p.m. Night Tour

- Woljeonggyo Bridge
- Gyochon Village
- Donggung Palace and Wolji Pond
- Hwangridan-gil Street

WEDNESDAY, Oct. 25, 2023

7:30 a.m. - 8:00 a.m. Conference Registration

8:00 a.m. - 8:40 a.m. Keynote Presentation 6

Towards Reliable and Versatile Laser Shock Application: from Laser to Parts Dr. Laurent Berthe (Lab PIMM CNRS, France)